Celanese
The chemistry inside innovation™

CELCON® LW25-S2

Low wear/friction, silicone, low speed, high load, improved toughness
Celcon® LW25-S2 acetal copolymer is a low flow, improved toughness product formulated with a low level of silicone to reduce friction and improved wear resistance.

Rheological properties

Melt volume-flow rate	2.1	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile Modulus	2350	MPa	ISO 527-1/-2
Yield stress, 50mm/min	54	MPa	ISO 527-1/-2
Yield strain, 50mm/min	20	%	ISO 527-1/-2
Flexural Modulus	2300	MPa	ISO 178
Flexural Stress at 3.5%	65	MPa	ISO 178
Charpy notched impact strength, 23°C	9	kJ/m^2	ISO 179/1eA
Izod notched impact strength, 23°C	9	kJ/m^2	ISO 180/1A

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	90	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel	110	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	110	E-6/K	ISO 11359-1/-2

Other properties

Density	1380	kg/m^3	ISO 1183

Injection

Drying Temperature	100 - 120	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Max. mould temperature	80 - 120	°C
Back pressure	4	MPa
Injection speed	slow	

Additional information

Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material. Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F).

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Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.

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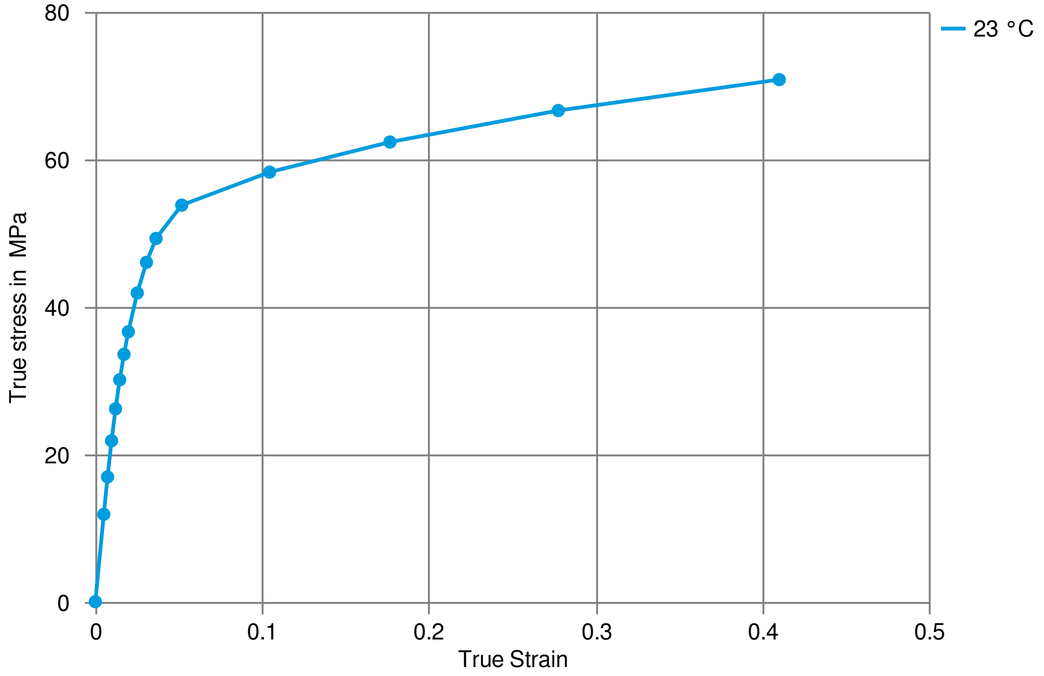
True stress-strain



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Processing Texts

Pre-drying	Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.
Injection molding	Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material. Melt Temperature: Preferred range 182-199 C (360-390 F). Melt temperature should never exceed 230 C (450 F). Mold Surface Temperature: Preferred range 82-93 C (180-200 F) especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. Wall thickness greater than 3mm (1/8 in.) may use a cooler (65 C/150 F) mold surface temperature and wall thickness over 6mm (1/4 in.) may use a cold mold surface down to 25 C (80 F). In general, mold surface temperatures lower than 82 C (180 F) may hinder weld line formation and produce a hazy surface or a surface with flow lines, pits and other included defects that can hinder part performance.
Injection molding Preprocessing	Drying is generally not required because Celcon® and Hostaform® acetal copolymers are not hydroscopic nor are they degraded by moisture during processing. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%
Injection molding Postprocessing	Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

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